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## DS91D180/DS91C180

## 100 MHz M-LVDS Line Driver/Receiver Pair

#### **General Description**

The DS91D180 and DS91C180 are 100 MHz M-LVDS (Multipoint Low Voltage Differential Signaling) line driver/receiver pairs designed for applications that utilize multipoint networks (e.g. clock distribution in ATCA and uTCA based systems). M-LVDS is a new bus interface standard (TIA/EIA-899) optimized for multidrop networks. Controlled edge rates, tight input receiver thresholds and increased drive strength are sone of the key enhancments that make M-LVDS devices an ideal choice for distributing signals via multipoint networks.

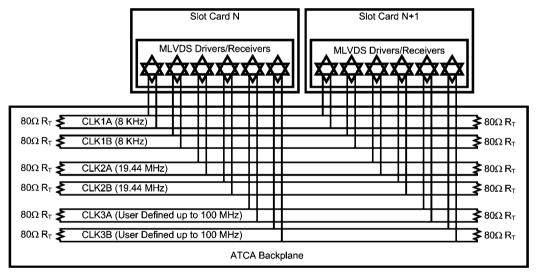
The DS91D180/DS91C180 driver input accepts LVTTL/LVCMOS signals and converts them to differential M-LVDS signal levels. The DS91D180/DS91C180 receiver accepts low voltage differential signals (LVDS, B-LVDS, M-LVDS, LV-PECL and CML) and converts them to 3V LVCMOS signals. The DS91D180 device has a M-LVDS type

1 receiver input with no offset. The DS91C180 device has a type 2 receiver input which enable fails afe functionality.

#### **Features**

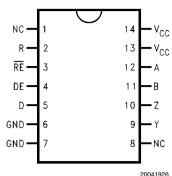
- DC to 100+ MHz / 200+ Mbps low power, low EMI operation
- Optimal for ATCA, uTCA clock distribution networks
- Meets or exceeds TIA/EIA-899 M-LVDS Standard
- Wide Input Common Mode Voltage for Increased Noise Immunity
- DS91D180 has type 1 receiver input
- DS91C180 has type 2 receiver input for fail-safe functionality
- Industrial temperature range
- Space saving SOIC-14 package (JEDEC MS-012)

### Typical Application in an ATCA Clock Distribution Network



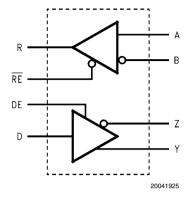
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## **Connection Diagram**



Top View
Order Number DS91D180TMA, DS91C180TMA
See NS Package Number M14A

## **Logic Diagram**



## **Ordering Information**

Order Number	Receiver Input	Function	Package Type
DS91D180TMA	type 1	Data (0V threshold receiver)	SOIC/M14A
DS91C180TMA	type 2	Control (offset fail-safe receiver)	SOIC/M14A

## **M-LVDS Receiver Types**

The EIA/TIA-899 M-LVDS standard specifies two different types of receiver input stages. A type 1 receiver has a conventional threshold that is centered at the midpoint of the input amplitude,  $V_{\text{ID}}/2$ . A type 2 receiver has a built in offset that is 100mV greater than  $V_{\text{ID}}/2$ . The type 2 receiver offset acts as a failsafe circuit where open or short circuits at the input will always result in the output stage being driven to a low logic state.

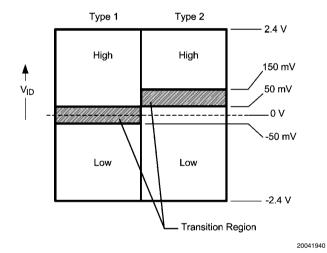


FIGURE 1. M-LVDS Receiver Input Thresholds

#### **Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Maximum Package Power Dissipation at +25°C

SOIC Package 1.1 W
Derate SOIC Package 8.8 mW/°C above +25°C

Thermal Resistance (4-Layer, 2 oz. Cu, JEDEC)

 $\theta_{JA}$  113.7 °C/W  $\theta_{JC}$  36.9 °C/W Maximum Junction Temperature 150°C Storage Temperature Range -65°C to +150°C

 Lead Temperature
 (Soldering, 4 seconds)
 260°C

 ESD Ratings:
 (HBM 1.5kΩ, 100pF)
 ≥ 5 kV

 (EIAJ 0Ω, 200pF)
 ≥ 250 V

 (CDM 0Ω, 0pF)
 ≥ 1000 V

# Recommended Operating Conditions

	Min	Тур	Max	Units
Supply Voltage, V <sub>CC</sub>	3.0	3.3	3.6	V
Voltage at Any Bus Terminal	-1.4		+3.8	V
(Separate or Common-Mode)				
Differential Input Voltage V <sub>ID</sub>			2.4	V
High Level Input Voltage V <sub>IH</sub>	2.0		$V_{CC}$	V
Low Level Input Voltage V <sub>IL</sub>	0		8.0	V
Operating Free Air				
Temperature T <sub>A</sub>	-40	+25	+85	°C

#### **Electrical Characteristics**

Over recommended operating supply and temperature ranges unless otherwise specified. (Note 2, Note 3, Note 4, Note 8)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
M-LVDS D	river						
IV <sub>YZ</sub> I	Differential output voltage magnitude	$R_L = 50\Omega, C_L = 5pF$		480		650	mV
$\Delta V_{YZ}$	Change in differential output voltage magnitude between logic states	Figure 2 and Figure 4		-50	0	+50	mV
V <sub>OS(SS)</sub>	Steady-state common-mode output voltage	$R_L = 50\Omega$ , $C_L = 5pF$		0.3	1.8	2.1	V
$ \Delta V_{OS(SS)} $	Change in steady-state common-mode output voltage between logic states	Figure 2 and Figure 3		0		+50	mV
V <sub>OS(PP)</sub>	Peak-to-peak common-mode output voltage	(V <sub>OS(pp)</sub> @ 500KHz clock)			143		mV
V <sub>Y(OC)</sub>	Maximum steady-state open-circuit output voltage	Figure 5		0		2.4	V
V <sub>Z(OC)</sub>	Maximum steady-state open-circuit output voltage			0		2.4	V
V <sub>P(H)</sub>	Voltage overshoot, low-to-high level output	$R_1 = 50\Omega, C_1 = 5pF,$				1.2V <sub>SS</sub>	V
V <sub>P(L)</sub>	Voltage overshoot, high-to-low level output	C <sub>D</sub> = 0.5pF Figure 7 and Figure 8 (Note 9)		-0.2V <sub>S</sub>			V
I <sub>IH</sub>	High-level input current (LVTTL inputs)	V <sub>IH</sub> = 2.0V		-15		15	μA
I <sub>IL</sub>	Low-level input current (LVTTL inputs)	V <sub>IL</sub> = 0.8V		-15		15	μA
V <sub>IKL</sub>	Input Clamp Voltage (LVTTL inputs)	I <sub>IN</sub> = -18 mA		-1.5			V
I <sub>os</sub>	Differential short-circuit output current	Figure 6		-43		43	mA
M-LVDS R	eceiver						
V <sub>IT+</sub>	Positive-going differential input voltage threshold	See Function Tables	Type 1		20	50	mV
			Type 2		94	150	mV
$V_{IT-}$	Negative-going differential input voltage threshold	See Function Tables	Type 1	-50	20		mV
		Type 2		50	94		mV
V <sub>OH</sub>	High-level output voltage	$I_{OH} = -8mA$		2.4	2.7		V
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 8mA			0.28	0.4	V
l <sub>oz</sub>	TRI-STATE output current	V <sub>O</sub> = 0V or 3.6V		-10		10	μΑ
I <sub>OSR</sub>	Short circuit Rrceiver output current (LVTTL Output)	$V_O = 0V$		-90	-48		mA

Symbol	Parameter	Conditions	Min	Тур	Max	Units
M-LVDS B	us (Input and Output) Pins					
$I_A, I_Y$	Receiver input or driver high-impedance output current	V <sub>A,Y</sub> = 3.8V, V <sub>B,Z</sub> = 1.2V, DE = GND			32	μА
		$V_{A,Y} = 0V \text{ or } 2.4V, V_{B,Z} = 1.2V, DE$ = GND	-20		+20	μА
		$V_{A,Y} = -1.4V, V_{B,Z} = 1.2V,$ DE = GND	-32			μA
I <sub>B</sub> , I <sub>Z</sub>	Receiver input or driver high-impedance output current	$V_{B,Z} = 3.8V, V_{A,Y} = 1.2V,$ DE = GND			32	μА
		$V_{B,Z} = 0V \text{ or } 2.4V, V_{A,Y} = 1.2V, DE = GND$	-20		+20	μА
		$V_{B,Z} = -1.4V, V_{A,Y} = 1.2V,$ DE = GND	-32			μА
$I_{AB}, I_{YZ}$	Receiver input or driver high-impedance output differential current ( $I_A - I_B$ or $I_Y - I_Z$ )	$V_{A,Y} = V_{B,Z}, -1.4V \le V \le 3.8V, DE$ = GND	-4		+4	μΑ
I <sub>A(OFF)</sub> , I <sub>Y(OFF)</sub>	Receiver input or driver high-impedance output power-off current	$V_{A,Y} = 3.8V, V_{B,Z} = 1.2V,$ $DE = 0V$ $0V \le V_{CC} \le 1.5V$			32	μА
		$V_{A,Y} = 0V \text{ or } 2.4V, V_{B,Z} = 1.2V,$ $DE = 0V$ $0V \le V_{CC} \le 1.5V$	-20		+20	μА
		$V_{A,Y} = -1.4V, V_{B,Z} = 1.2V,$ $DE = 0V$ $0V \le V_{CC} \le 1.5V$	-32			μА
I <sub>B(OFF)</sub> , I <sub>Z(OFF)</sub>	Receiver input or driver high-impedance output power-off current	$V_{B,Z} = 3.8V, V_{A,Y} = 1.2V,$ $DE = 0V$ $0V \le V_{CC} \le 1.5V$			32	μΑ
		$V_{B,Z} = 0V \text{ or } 2.4V, V_{A,Y} = 1.2V,$ DE = 0V $0V \le V_{CC} \le 1.5V$	-20		+20	μА
		$V_{B,Z} = -1.4V, V_{A,Y} = 1.2V,$ $DE = 0V$ $0V \le V_{CC} \le 1.5V$	-32			μА
I <sub>AB(OFF)</sub> , I <sub>YZ(OFF)</sub>	Receiver input or driver high-impedance output power-off differential current $(I_{A(OFF)} - I_{B(OFF)} \text{ or } I_{Y(OFF)} - I_{Z(OFF)})$	$V_{A,Y} = V_{B,Z}, -1.4V \le V \le 3.8V,$ $DE = 0V$ $0V \le V_{CC} \le 1.5V$	-4		+4	μА
C <sub>A</sub> , C <sub>B</sub>	Receiver input capacitance	V <sub>CC</sub> = OPEN		5.1		pF
C <sub>Y</sub> , C <sub>Z</sub>	Driver output capacitance			8.5		pF
C <sub>AB</sub>	Receiver input differential capacitance	1		2.5		pF
C <sub>YZ</sub>	Driver output differential capacitance			5.5		pF
C <sub>A/B</sub> ,	Receiver input or driver output capacitance balance $(C_A/C_B \text{ or } C_Y/C_Z)$			1.0		
	CURRENT (V <sub>CC</sub> )					
I <sub>CCD</sub>	Driver Supply Current	$R_L = 50\Omega$ , $DE = V_{CC}$ , $\overline{RE} = V_{CC}$		17	29.5	mA
I <sub>CCZ</sub>	TRI-STATE Supply Current	$DE = GND, \overline{RE} = V_{CC}$		7	9.0	mA
JUL	Receiver Supply Current	DE = GND, RE = GND		14	18.5	mA
I <sub>CCR</sub>	Ineceiver Supply Current	IDE - GIVD, ITE - GIVD			10.0	

#### **Switching Characteristics**

Over recommended operating supply and temperature ranges unless otherwise specified. (Note 3, Note 8)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
DRIVER AC	SPECIFICATION					
t <sub>PLH</sub>	Differential Propagation Delay Low to High	$R_L = 50\Omega, C_L = 5 pF,$	1.0	3.4	5.5	ns
t <sub>PHL</sub>	Differential Propagation Delay High to Low	C <sub>D</sub> = 0.5 pF	1.0	3.1	5.5	ns
t <sub>SKD1</sub> (t <sub>sk(p)</sub> )	Pulse Skew It <sub>PLHD</sub> – t <sub>PHLD</sub> I ( <i>Note 5</i> , <i>Note 9</i> )	Figure 7 and Figure 8		300	420	ps
t <sub>SKD3</sub>	Part-to-Part Skew (Note 6, Note 9)				1.9	ns
t <sub>TLH</sub> (t <sub>r</sub> )	Rise Time (Note 9)		1.0	1.8	3.0	ns
t <sub>THL</sub> (t <sub>f</sub> )	Fall Time (Note 9)		1.0	1.8	3.0	ns
t <sub>PZH</sub>	Enable Time (Z to Active High)	$R_L = 50\Omega, C_L = 5 pF,$			8	ns
t <sub>PZL</sub>	Enable Time (Z to Active Low)	C <sub>D</sub> = 0.5 pF			8	ns
t <sub>PLZ</sub>	Disable Time (Active Low to Z)	Figure 9 and Figure 10			8	ns
t <sub>PHZ</sub>	Disable Time (Active High to Z)	7			8	ns
t <sub>JIT</sub>	Random Jitter, RJ (Note 9)	100MHz clock pattern (Note 7)		2.5	5.5	psrms
f <sub>MAX</sub>	Maximum Data Rate		200			Mbps
RECEIVER A	C SPECIFICATION		•			
t <sub>PLH</sub>	Propagation Delay Low to High	C <sub>L</sub> = 15 pF	2.0	4.7	7.5	ns
t <sub>PHL</sub>	Propagation Delay High to Low	Figure 11 Figure 12and Figure 13	2.0	5.3	7.5	ns
$t_{SKD1} (t_{sk(p)})$	Pulse Skew It <sub>PLHD</sub> – t <sub>PHLD</sub> I ( <i>Note 5</i> , <i>Note 9</i> )			0.6	1.9	ns
t <sub>SKD3</sub>	Part-to-Part Skew (Note 6, Note 9)				1.5	ns
t <sub>TLH</sub> (t <sub>r</sub> )	Rise Time (Note 9)		0.5	1.2	3.0	ns
t <sub>THL</sub> (t <sub>f</sub> )	Fall Time (Note 9)		0.5	1.2	3.0	ns
t <sub>PZH</sub>	Enable Time (Z to Active High)	$R_L = 500\Omega, C_L = 15 pF$			10	ns
t <sub>PZL</sub>	Enable Time (Z to Active Low)	Figure 14 and Figure 15			10	ns
t <sub>PLZ</sub>	Disable Time (Active Low to Z)	1			10	ns
t <sub>PHZ</sub>	Disable Time (Active High to Z)	1			10	ns
f <sub>MAX</sub>	Maximum Data Rate		200			Mbps

**Note 1:** "Absolute Maximum Ratings" are those beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the device should be operated at these limits. The tables of "Electrical Characteristics" provide conditions for actual device operation.

Note 2: All currents into device pins are positive; all currents out of device pins are negative. All voltages are referenced to device ground unless otherwise specified.

**Note 3:** All typicals are given for  $V_{CC} = 3.3V$  and  $T_A = 25^{\circ}C$ .

Note 4: The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this datasheet.

Note 5: t<sub>SKD1</sub>, |t<sub>PLHD</sub> - t<sub>PHLD</sub>|, is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.

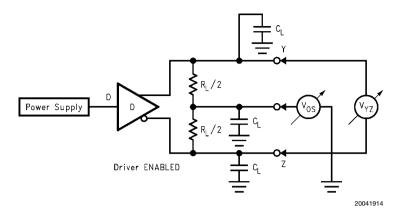
Note 6: t<sub>SKD3</sub>, Part-to-Part Skew, is defined as the difference between the minimum and maximum specified differential propagation delays. This specification applies to devices at the same V<sub>CC</sub> and within 5°C of each other within the operating temperature range.

Note 7: Stimulus and fixture jitter has been subtracted.

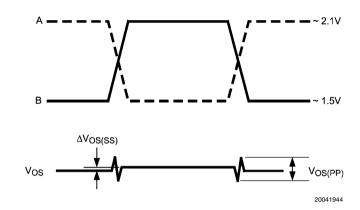
Note 8:  $C_L$  includes fixture capacitance and  $C_D$  includes probe capacitance.

Note 9: Not production tested. Guaranteed by a statistical analysis on a sample basis at the time of characterization.

## **Test Circuits and Waveforms**



**FIGURE 2. Differential Driver Test Circuit** 



**FIGURE 3. Differential Driver Waveforms** 

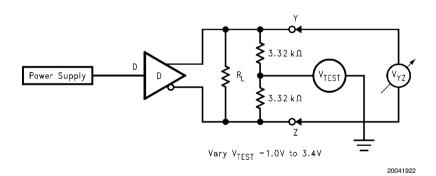


FIGURE 4. Differential Driver Full Load Test Circuit

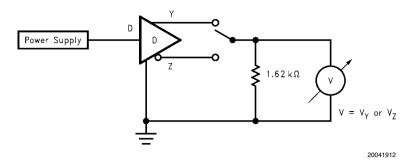


FIGURE 5. Differential Driver DC Open Test Circuit

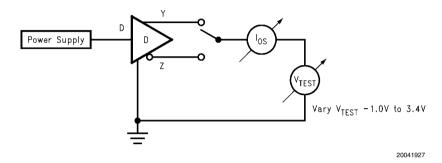


FIGURE 6. Differential Driver Short-Circuit Test Circuit

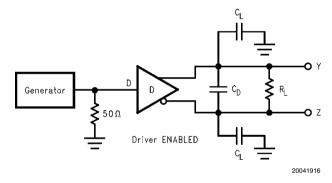


FIGURE 7. Driver Propagation Delay and Transition Time Test Circuit

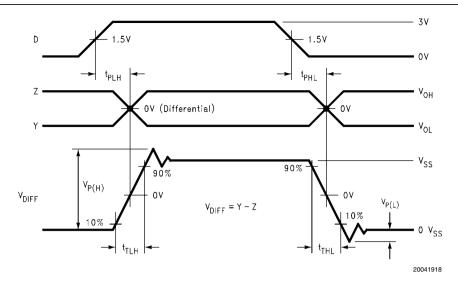


FIGURE 8. Driver Propagation Delays and Transition Time Waveforms

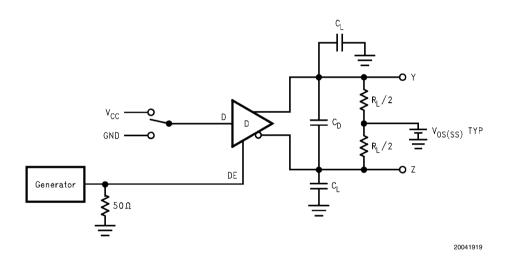


FIGURE 9. Driver TRI-STATE Delay Test Circuit

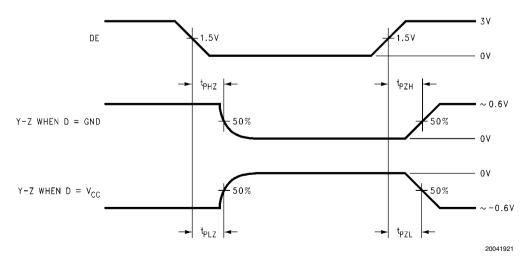


FIGURE 10. Driver TRI-STATE Delay Waveforms

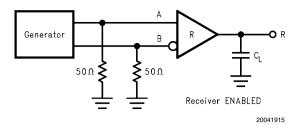


FIGURE 11. Receiver Propagation Delay and Transition Time Test Circuit

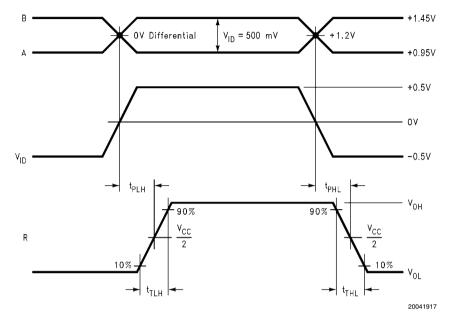


FIGURE 12. Type 1 Receiver Propagation Delay and Transition Time Waveforms

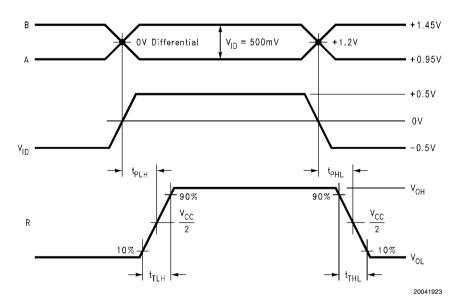


FIGURE 13. Type 2 Receiver Propagation Delay and Transition Time Waveforms

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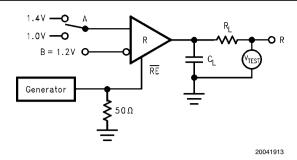


FIGURE 14. Receiver TRI-STATE Delay Test Circuit

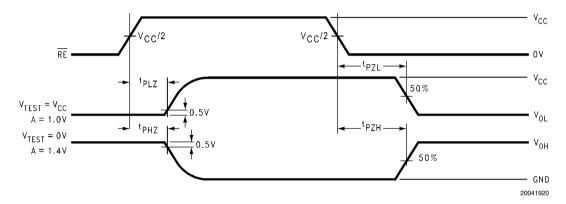


FIGURE 15. Receiver TRI-STATE Delay Waveforms

## **Function Tables**

#### DS91D180/DS91C180 Transmitting

Inp	uts	Out	outs
DE	D	Z	Υ
2.0V	2.0V	L	Н
2.0V	0.8V	Н	L
0.8V	Х	Z	Z

X — Don't care condition

Z — High impedance state

#### **DS91D180 Receiving**

lr	nputs	Output			
RE	R				
0.8V	≥ +0.05V	Н			
0.8V	≤ -0.05V	L			
0.8V	0V	Х			
2.0V	Х	Z			

X — Don't care condition

Z — High impedance state

#### **DS91C180 Receiving**

lı	nputs	Output
RE	R	
0.8V	≥ +0.15V	Н
0.8V	≤ +0.05V	L
0.8V	0V	L
2.0V	Х	Z

X — Don't care condition

Z — High impedance state

#### **DS91D180 Receiver Input Threshold Test Voltages**

Applied Voltages		Resulting Differential Input Voltage	Resulting Common-Mode Input Voltage	Receiver Output
V <sub>IA</sub>	V <sub>IB</sub>	V <sub>ID</sub>	V <sub>IC</sub>	R
2.400V	0.000V	2.400V	1.200V	Н
0.000V	2.400V	-2.400V	1.200V	L
3.800V	3.750V	0.050V	3.775V	Н
3.750V	3.800V	-0.050V	3.775V	L
-1.400V	-1.350V	-0.050V	−1.375V	Н
-1.350V	-1.400V	0.050V	-1.375V	L

H — High Level L — Low Level

Output state assumes that the receiver is enabled  $(\overline{RE} = L)$ 

#### **DS91C180 Receiver Input Threshold Test Voltages**

Applied Voltages		Resulting Differential Input Voltage	Resulting Common-Mode Input Voltage	Receiver Output
V <sub>IA</sub>	V <sub>IB</sub>	V <sub>ID</sub>	V <sub>IC</sub>	R
2.400V	0.000V	2.400V	1.200V	Н
0.000V	2.400V	-2.400V	1.200V	L
3.800V	3.650V	0.150V	3.725V	Н
3.800V	3.750V	0.050V	3.775V	L
-1.250V	-1.400V	0.150V	-1.325V	Н
-1.350V	-1.400V	0.050V	−1.375V	L

H — High Level

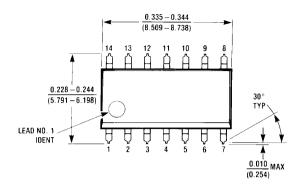
L — Low Level Output state assumes that the receiver is enabled  $(\overline{RE}$  = L)

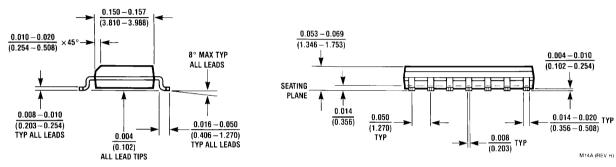
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## **Pin Descriptions**

Pin No.	Name	Description
1, 8	NC	No connect.
2	R	Receiver output pin
3	RE	Receiver enable pin: When $\overline{RE}$ is high, the receiver is disabled. When $\overline{RE}$ is low or open, the receiver is enabled.
4	DE	Driver enable pin: When DE is low, the driver is disabled. When DE is high, the driver is enabled.
5	D	Driver input pin
6, 7	GND	Ground pin
9	Υ	Non-inverting driver output pin
10	Z	Inverting driver output pin
11	В	Inverting receiver input pin
12	Α	Non-inverting receiver input pin
13, 14	V <sub>CC</sub>	Power supply pin, +3.3V ± 0.3V

## Physical Dimensions inches (millimeters) unless otherwise noted





Order Number DS91D180TMA, DS91C180TMA See NS package Number M14A

#### **Notes**

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Data Converters	www.national.com/adc	Samples	www.national.com/samples
Interface	www.national.com/interface	Eval Boards	www.national.com/evalboards
LVDS	www.national.com/lvds	Packaging	www.national.com/packaging
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback
Voltage Reference	www.national.com/vref	Design Made Easy	www.national.com/easy
PowerWise® Solutions	www.national.com/powerwise	Solutions	www.national.com/solutions
Serial Digital Interface (SDI)	www.national.com/sdi	Mil/Aero	www.national.com/milaero
Temperature Sensors	www.national.com/tempsensors	SolarMagic™	www.national.com/solarmagic
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